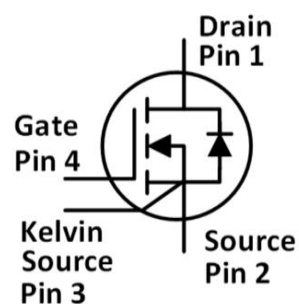
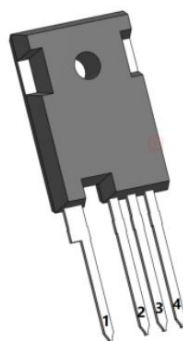


2000V N-Channel MOSFET
Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Optimized package with separate driver source pin
- Easy to parallel and simple to drive
- ROHS Compliant, Halogen free


Application

- EV motor drive
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Solar inverters
- EV charging

Ordering Information

Part Number	Marking	Package	Packaging
ASC30N2000MT4PB	ASC30N2000MT4	TO-247-4	Tube

Absolute Maximum Ratings(Tc=25℃)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	2000	V
I_D	Drain Current(continuous)at Tc=25℃	30	A
I_D	Drain Current(continuous)at Tc=100℃	20	A
I_{DM}	Drain Current (pulsed)	78	A
V_{GS}	Gate-Source Voltage	-10/+22V	V
P_D	Power Dissipation T _C = 25℃	258	W
T _J , Tstg	Junction and Storage Temperature Range	-55 to +175	℃

Electrical Characteristics(T_J = 25℃ unless otherwise specified)
Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu A, V_{GS}=0V$	2000			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=2000V,$ $V_{GS}=0V, T_J=25^\circ C$		1	100	μA
I_{GSS}	Gate-body Leakage Current	$V_{DS}=0V ; V_{GS}=-10$ to 20V		10	250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=20mA$	1.8	2.6	3.5	V
$V_{GS(on)}$	Recommended turn-on Voltage	Static		15		V
$V_{GS(off)}$	Recommended turn-off Voltage			-3		V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=15V, I_D=20A$		98	125	mΩ
		$V_{GS}=15V, I_D=20A$ $T_J=175^\circ C$		172		mΩ
		$V_{GS}=18V, I_D=20A$		88		mΩ

Typical Performance-Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input Capacitance	$V_{DS}=1000V, f=1MHz,$ $V_{AC}=25mV$		2865		pF
C_{oss}	Output Capacitance			97		pF
C_{rss}	Reverse Transfer Capacitance			3		pF
E_{oss}	C_{oss} Stored Energy	$V_{DS}=1000V, f=1MHz$		50.7		μJ
E_{on}	Turn-On Energy (Body Diode)	$V_{DS}=1200V, V_{GS}=-3/15V,$ $I_D=20A, L=150\mu H, T_J=175^\circ C$		495		μJ
E_{off}	Turn-Off Energy (Body Diode)			121		μJ
Q_g	Total Gate Charge	$V_{DS}=1200V, V_{GS}=-3V/15V,$ $I_D=20A$		62		nC
Q_{gs}	Gate-source Charge			18		nC
Q_{gd}	Gate-Drain Charge			16		nC
$R_{G(int)}$	Internal Gate Resistance	$f=1MHz, V_{AC}=25mV$		2.6		Ω
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=1200V, V_{GS}=-3V/15V,$ $I_D=20A, L=150\mu H$ $R_{ext}=2.5\Omega$		42		ns
t_r	Rise Time			20		ns
$t_{d(off)}$	Turn-off Delay Time			27		ns
t_f	Fall Time			11		ns

Typical Performance-Reverse Diode($T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{FSD}	Forward Voltage	$V_{GS}=0V, I_F=10A, T_J=25^\circ C$		3.9	6	V
		$V_{GS}=0V, I_F=10A, T_J=175^\circ C$		3.5	6	V
I_S	Continuous Diode Forward Current	$V_{GS}=0V, T_C=25^\circ C$		20		A
t_{rr}	Reverse Recovery Time	$V_{GS}=-3V, I_F=10A,$ $V_R=1200V, di/dt=900$ $A/\mu s, T_J=175^\circ C$		36		nS
Q_{rr}	Reverse Recovery Charge			285		nC
I_{rrm}	Peak Reverse Recovery Current			13.5		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.58	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	40	$^\circ C/W$

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of $T_J(max)=175^\circ C$

Electrical Characteristics

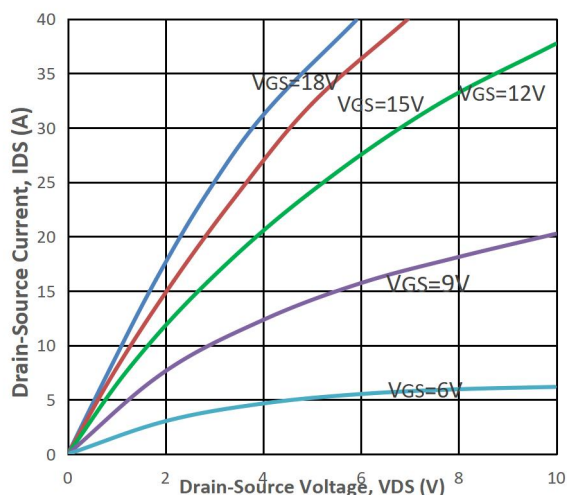
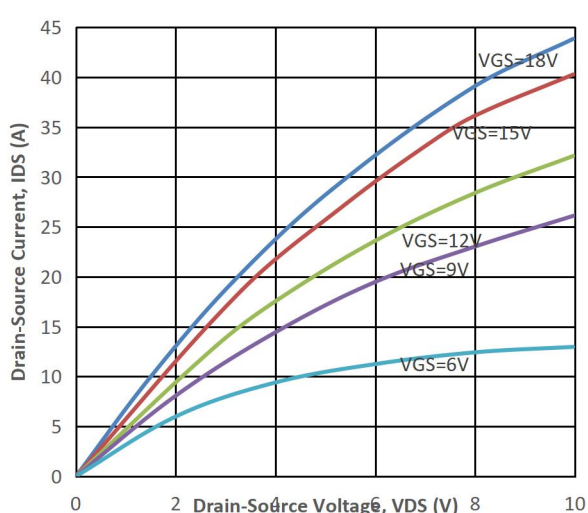
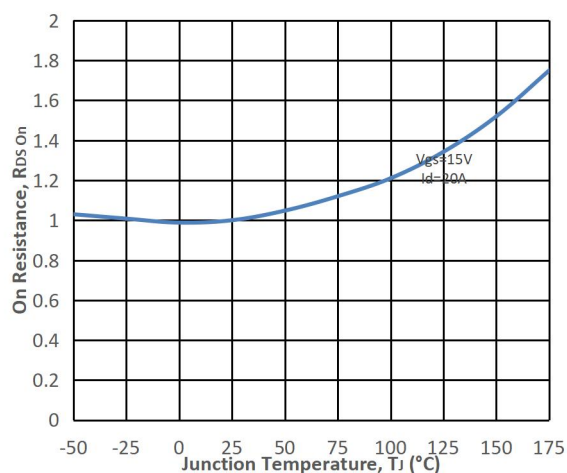
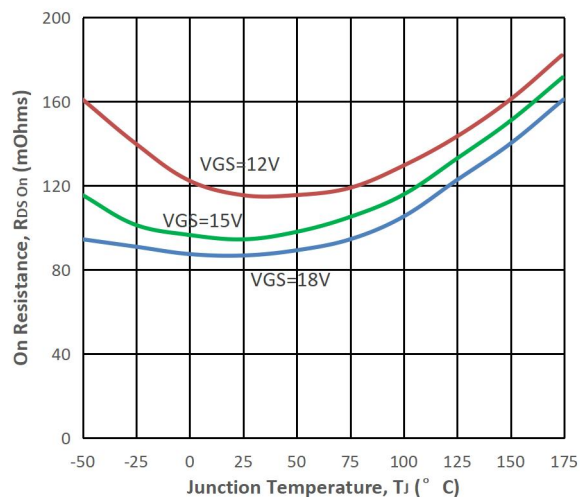
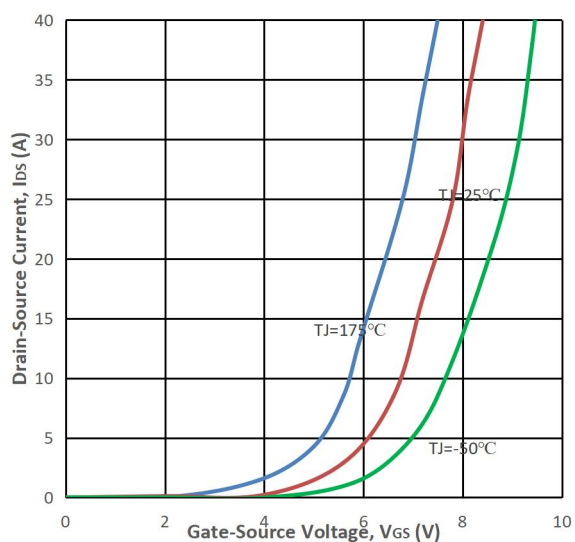
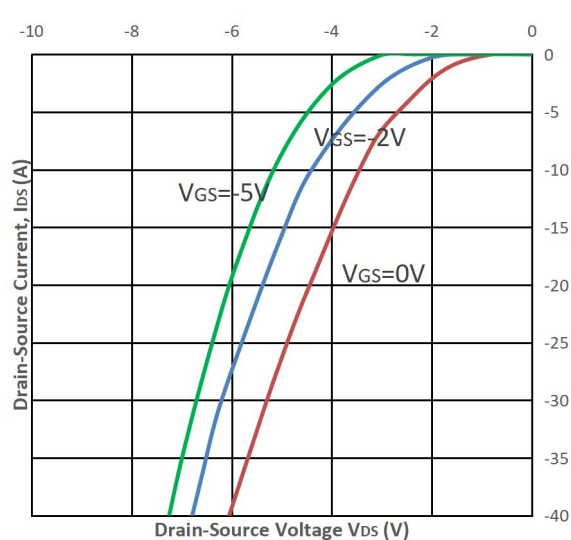
Fig1. Output characteristics ($T_J = 25^\circ\text{C}$)

Fig2. Output characteristics ($T_J = 175^\circ\text{C}$)

Fig3. Normalized On-Resistance vs. Temperature

Fig4. On-Resistance vs. Temperature

Fig5. Transfer Characteristic

Fig6. Body Diode Characteristic at 25°C


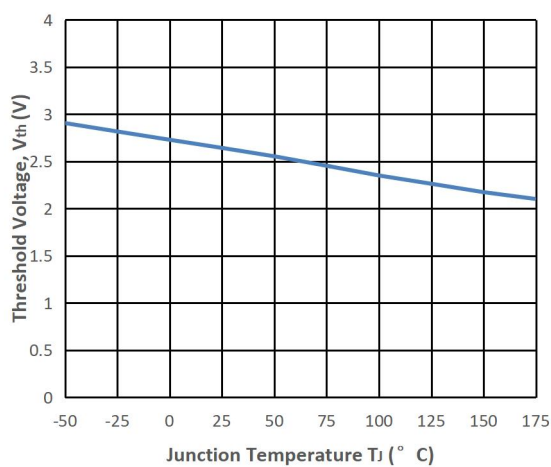
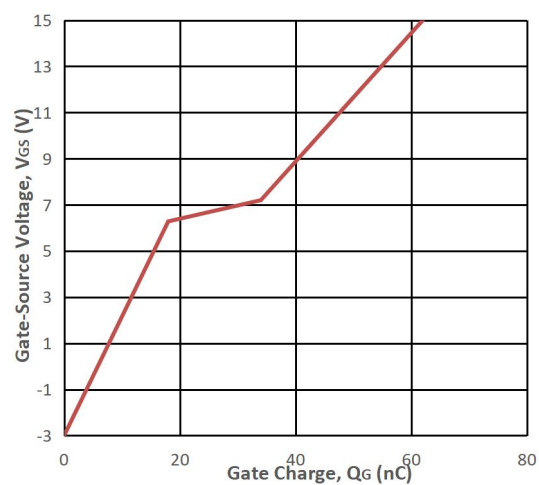
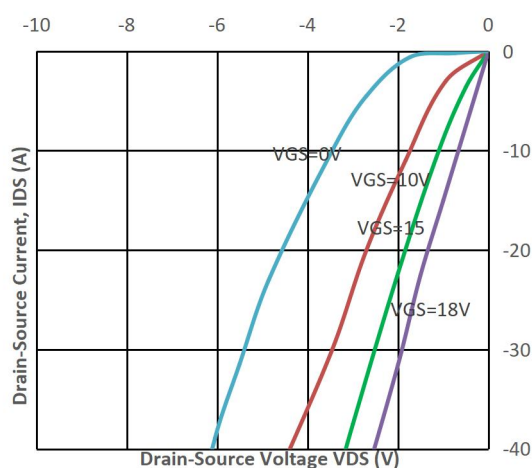
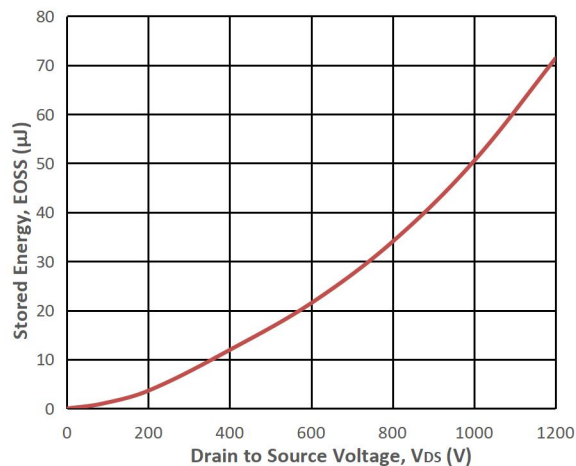
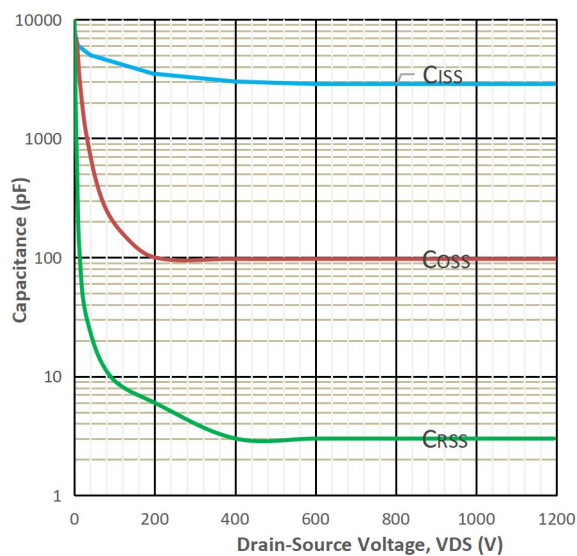
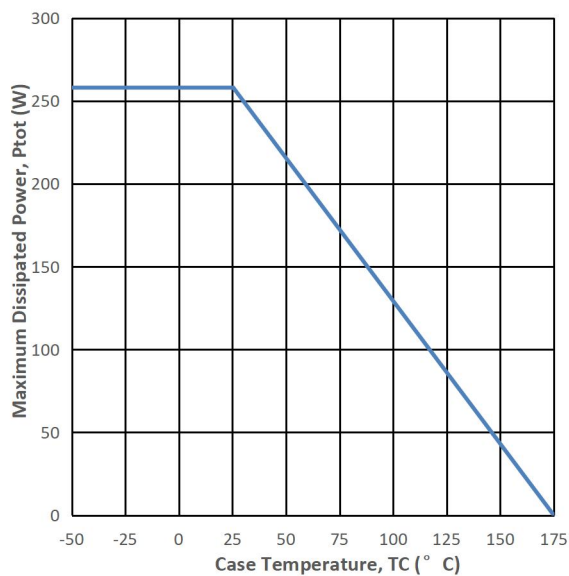
Fig7. Threshold Voltage vs. Temperature

Fig8. Gate Charge Characteristics

Fig9. 3rd Quadrant Characteristic at 25 °C

Fig10. Output Capacitor Stored Energy

Fig11. Capacitances vs. Drain-Source

Fig12. Max Power Dissipation Derating Vs Tc


Fig13. Switching Energy vs. Drain Current

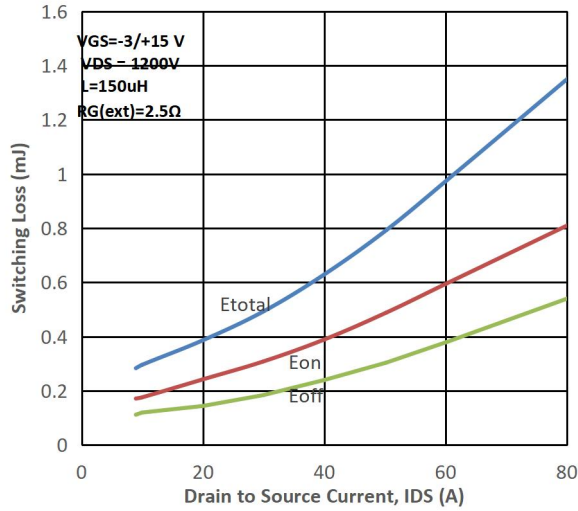


Fig14. Switching Energy vs. $R_{G(ext)}$

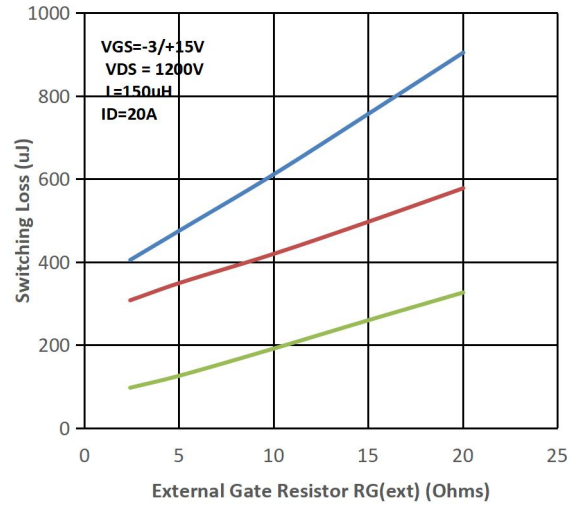


Fig15. Switching Energy vs. Temperature

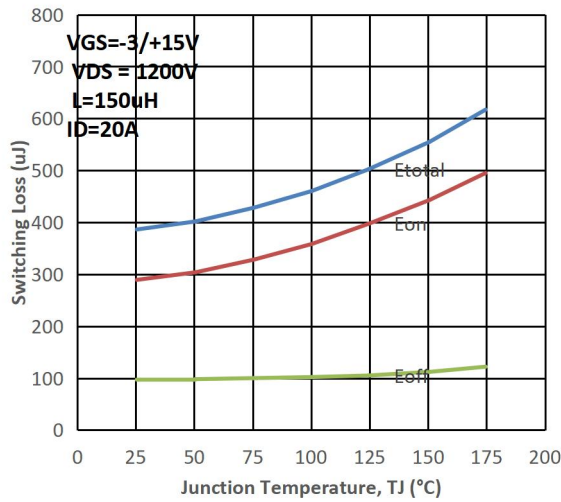


Fig16. Switching Times vs. $R_{G(ext)}$

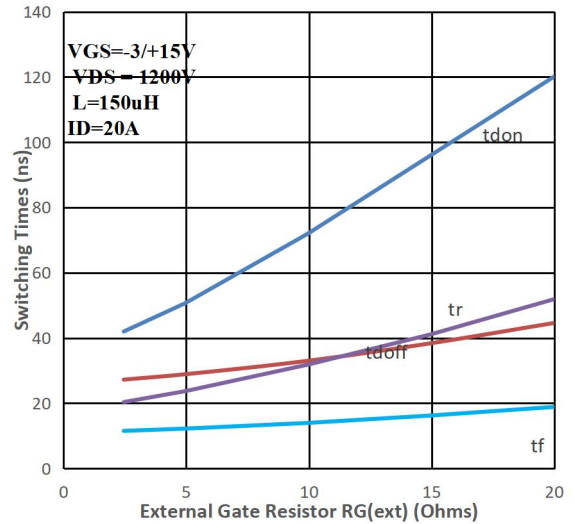


Fig17. Transient Thermal Impedance

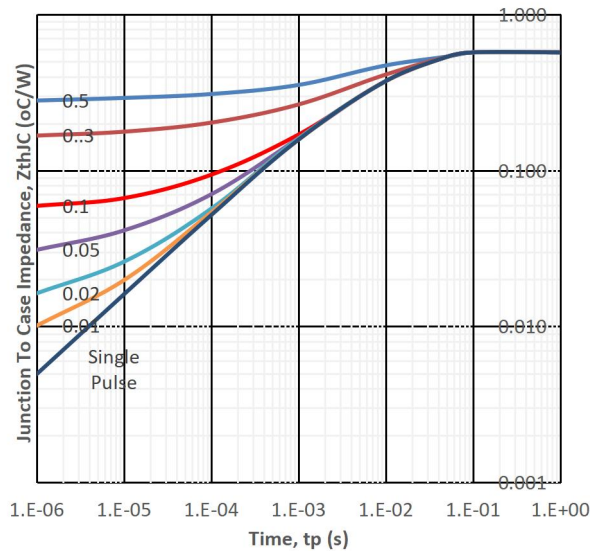
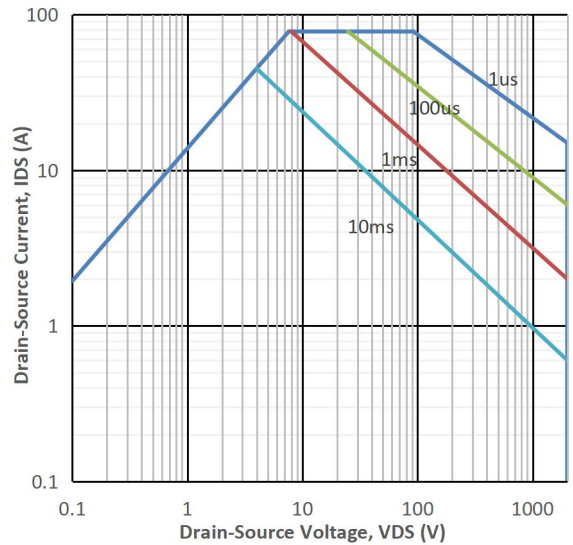
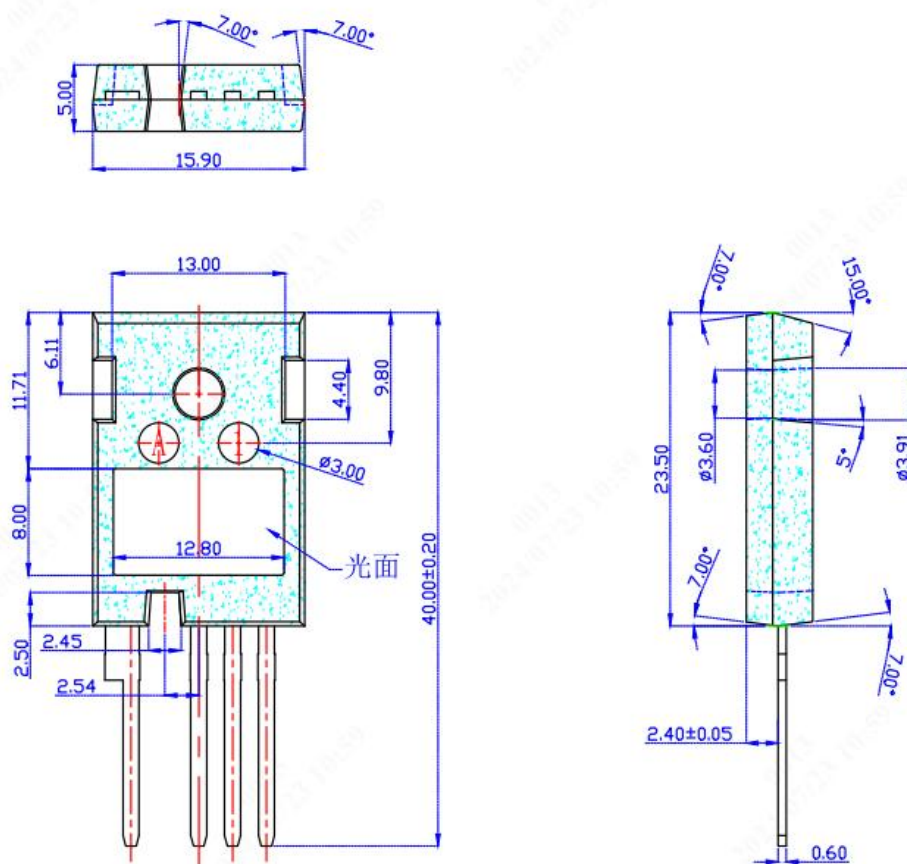


Fig18. Safe Operating Area



Package Drawing(mm):



Notes:

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Contact Info:

- Tel: +86 755-89300160
- Web: www.astsic.com
- Add: No.1 Rongtian Rd., Kendzi Street, Pingshan District, Shenzhen, China

Offical Account:



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